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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	276480
Number of I/O	280
Number of Gates	1500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/m1a3pe1500-2fg484i">https://www.e-xfl.com/product-detail/microchip-technology/m1a3pe1500-2fg484i</a>

## Pro I/Os with Advanced I/O Standards

The ProASIC3E family of FPGAs features a flexible I/O structure, supporting a range of voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V). ProASIC3E FPGAs support 19 different I/O standards, including single-ended, differential, and voltage-referenced. The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported. Each I/O bank is subdivided into VREF minibanks, which are used by voltage-referenced I/Os. VREF minibanks contain 8 to 18 I/Os. All the I/Os in a given minibank share a common VREF line. Therefore, if any I/O in a given VREF minibank is configured as a VREF pin, the remaining I/Os in that minibank will be able to use that reference voltage.

Each I/O module contains several input, output, and enable registers. These registers allow the implementation of the following:

- Single-Data-Rate applications (e.g., PCI 66 MHz, bidirectional SSTL 2 and 3, Class I and II)
- Double-Data-Rate applications (e.g., DDR LVDS, B-LVDS, and M-LVDS I/Os for point-to-point communications, and DDR 200 MHz SRAM using bidirectional HSTL Class II)

ProASIC3E banks support M-LVDS with 20 multi-drop points.

Hot-swap (also called hot-plug, or hot-insertion) is the operation of hot-insertion or hot-removal of a card in a powered-up system.

Cold-sparing (also called cold-swap) refers to the ability of a device to leave system data undisturbed when the system is powered up, while the component itself is powered down, or when power supplies are floating.

## Specifying I/O States During Programming

You can modify the I/O states during programming in FlashPro. In FlashPro, this feature is supported for PDB files generated from Designer v8.5 or greater. See the [FlashPro User's Guide](#) for more information.

**Note:** PDB files generated from Designer v8.1 to Designer v8.4 (including all service packs) have limited display of Pin Numbers only.

1. Load a PDB from the FlashPro GUI. You must have a PDB loaded to modify the I/O states during programming.
2. From the FlashPro GUI, click PDB Configuration. A FlashPoint – Programming File Generator window appears.
3. Click the Specify I/O States During Programming button to display the Specify I/O States During Programming dialog box.
4. Sort the pins as desired by clicking any of the column headers to sort the entries by that header. Select the I/Os you wish to modify ([Figure 1-3 on page 1-7](#)).
5. Set the I/O Output State. You can set Basic I/O settings if you want to use the default I/O settings for your pins, or use Custom I/O settings to customize the settings for each pin. Basic I/O state settings:
  - 1 – I/O is set to drive out logic High
  - 0 – I/O is set to drive out logic Low
  - Last Known State – I/O is set to the last value that was driven out prior to entering the programming mode, and then held at that value during programming
  - Z -Tri-State: I/O is tristated

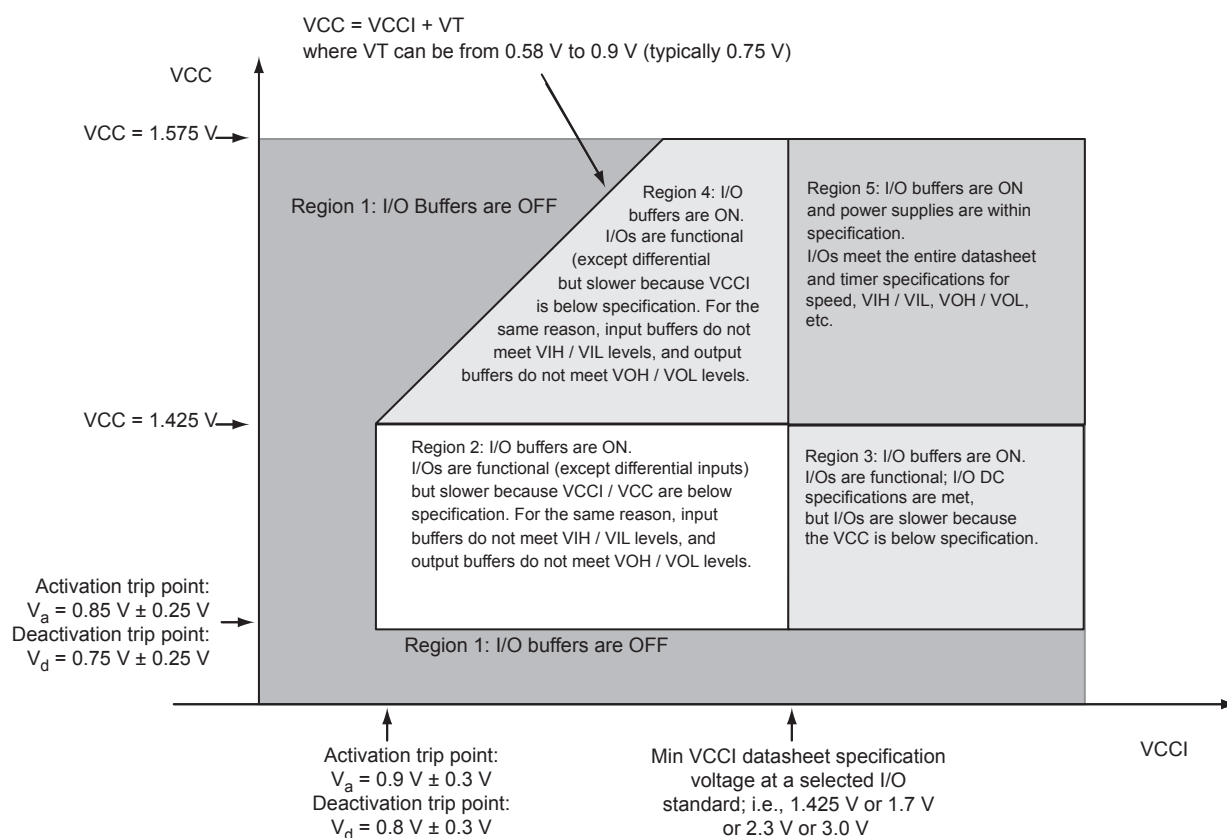
## PLL Behavior at Brownout Condition

Microsemi recommends using monotonic power supplies or voltage regulators to ensure proper power-up behavior. Power ramp-up should be monotonic at least until VCC and VCCPLXL exceed brownout activation levels. The VCC activation level is specified as 1.1 V worst-case (see [Figure 2-1 on page 2-4](#) for more details).

When PLL power supply voltage and/or VCC levels drop below the VCC brownout levels ( $0.75\text{ V} \pm 0.25\text{ V}$ ), the PLL output lock signal goes low and/or the output clock is lost. Refer to the "Power-Up/-Down Behavior of Low Power Flash Devices" chapter of the *ProASIC3E FPGA Fabric User's Guide* for information on clock and lock recovery.

## Internal Power-Up Activation Sequence

1. Core
2. Input buffers
3. Output buffers, after 200 ns delay from input buffer activation



**Figure 2-1 • I/O State as a Function of VCCI and VCC Voltage Levels**

## Calculating Power Dissipation

### Quiescent Supply Current

**Table 2-7 • Quiescent Supply Current Characteristics**

	A3PE600	A3PE1500	A3PE3000
Typical (25°C)	5 mA	12 mA	25 mA
Maximum (Commercial)	30 mA	70 mA	150 mA
Maximum (Industrial)	45 mA	105 mA	225 mA

**Notes:**

1. *IDD* Includes *VCC*, *VPUMP*, *VCCI*, and *VMV* currents. Values do not include I/O static contribution, which is shown in [Table 2-8](#) and [Table 2-9](#) on [page 2-7](#).
2. *-F* speed grade devices may experience higher standby *IDD* of up to five times the standard *IDD* and higher I/O leakage.

### Power per I/O Pin

**Table 2-8 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings**

	VMV (V)	Static Power PDC2 (mW) <sup>1</sup>	Dynamic Power PAC9 (μW/MHz) <sup>2</sup>
<b>Single-Ended</b>			
3.3 V LVTTTL/LVCMOS	3.3	–	17.39
3.3 V LVTTTL/LVCMOS – Schmitt trigger	3.3	–	25.51
3.3 V LVTTTL/LVCMOS Wide Range <sup>3</sup>	3.3	–	16.34
3.3 V LVTTTL/LVCMOS Wide Range – Schmitt trigger <sup>3</sup>	3.3	–	24.49
2.5 V LVCMOS	2.5	–	5.76
2.5 V LVCMOS – Schmitt trigger	2.5	–	7.16
1.8 V LVCMOS	1.8	–	2.72
1.8 V LVCMOS – Schmitt trigger	1.8	–	2.80
1.5 V LVCMOS (JESD8-11)	1.5	–	2.08
1.5 V LVCMOS (JESD8-11) – Schmitt trigger	1.5	–	2.00
3.3 V PCI	3.3	–	18.82
3.3 V PCI – Schmitt trigger	3.3	–	20.12
3.3 V PCI-X	3.3	–	18.82
3.3 V PCI-X – Schmitt trigger	3.3	–	20.12
<b>Voltage-Referenced</b>			
3.3 V GTL	3.3	2.90	8.23
2.5 V GTL	2.5	2.13	4.78
3.3 V GTL+	3.3	2.81	4.14
2.5 V GTL+	2.5	2.57	3.71

**Notes:**

1. *PDC2* is the static power (where applicable) measured on *VMV*.
2. *PAC9* is the total dynamic power measured on *VCC* and *VMV*.
3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD8b specification.



**Table 2-36 • 2.5 V LVCMOS Low Slew**
**Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**

Drive Strength	Speed Grade	$t_{DOUT}$	$t_{DP}$	$t_{DIN}$	$t_{PY}$	$t_{PYS}$	$t_{EOUT}$	$t_{ZL}$	$t_{ZH}$	$t_{LZ}$	$t_{HZ}$	$t_{ZLS}$	$t_{ZHS}$	Units
4 mA	Std.	0.66	12.00	0.04	1.51	1.66	0.43	12.23	11.61	2.72	2.20	14.46	13.85	ns
	–1	0.56	10.21	0.04	1.29	1.41	0.36	10.40	9.88	2.31	1.87	12.30	11.78	ns
	–2	0.49	8.96	0.03	1.13	1.24	0.32	9.13	8.67	2.03	1.64	10.80	10.34	ns
8 mA	Std.	0.66	8.73	0.04	1.51	1.66	0.43	8.89	8.01	3.10	2.93	11.13	10.25	ns
	–1	0.56	7.43	0.04	1.29	1.41	0.36	7.57	6.82	2.64	2.49	9.47	8.72	ns
	–2	0.49	6.52	0.03	1.13	1.24	0.32	6.64	5.98	2.32	2.19	8.31	7.65	ns
12 mA	Std.	0.66	6.77	0.04	1.51	1.66	0.43	6.90	6.11	3.37	3.39	9.14	8.34	ns
	–1	0.56	5.76	0.04	1.29	1.41	0.36	5.87	5.20	2.86	2.89	7.77	7.10	ns
	–2	0.49	5.06	0.03	1.13	1.24	0.32	5.15	4.56	2.51	2.53	6.82	6.23	ns
16 mA	Std.	0.66	6.31	0.04	1.51	1.66	0.43	6.42	5.73	3.42	3.52	8.66	7.96	ns
	–1	0.56	5.37	0.04	1.29	1.41	0.36	5.46	4.87	2.91	3.00	7.37	6.77	ns
	–2	0.49	4.71	0.03	1.13	1.24	0.32	4.80	4.28	2.56	2.63	6.47	5.95	ns
24 mA	Std.	0.66	5.93	0.04	1.51	1.66	0.43	6.04	5.70	3.49	4.00	8.28	7.94	ns
	–1	0.56	5.05	0.04	1.29	1.41	0.36	5.14	4.85	2.97	3.40	7.04	6.75	ns
	–2	0.49	4.43	0.03	1.13	1.24	0.32	4.51	4.26	2.61	2.99	6.18	5.93	ns

*Note:* For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

## 1.5 V LVCMOS (JESD8-11)

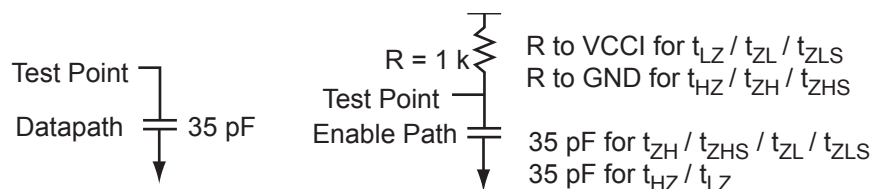
Low-Voltage CMOS for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 1.5 V input buffer and a push-pull output buffer.

**Table 2-41 • Minimum and Maximum DC Input and Output Levels**

1.5 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	μA <sup>4</sup>	μA <sup>4</sup>
2 mA	−0.3	0.30 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	16	13	10	10
4 mA	−0.3	0.30 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	4	4	33	25	10	10
6 mA	−0.3	0.30 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	6	6	39	32	10	10
8 mA	−0.3	0.30 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	8	8	55	66	10	10
12 mA	−0.3	0.30 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	12	12	55	66	10	10

**Notes:**

1. IIL is the input leakage current per I/O pin over recommended operation conditions where  $-0.3\text{ V} < V_{IN} < V_{IL}$ .
2. IIH is the input leakage current per I/O pin over recommended operating conditions  $V_{IH} < V_{IN} < V_{CCI}$ . Input current is larger when operating outside recommended ranges.
3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
4. Currents are measured at 85°C junction temperature.
5. Software default selection highlighted in gray.



**Figure 2-10 • AC Loading**

**Table 2-42 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	C <sub>LOAD</sub> (pF)
0	1.5	0.75	—	35

**Note:** \*Measuring point = Vtrip. See Table 2-15 on page 2-18 for a complete table of trip points.

## SSTL3 Class I

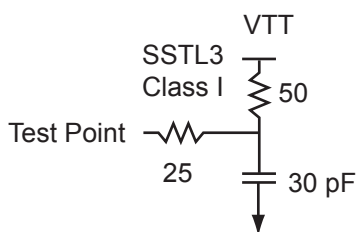
Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

**Table 2-72 • Minimum and Maximum DC Input and Output Levels**

SSTL3 Class I	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL	IIH
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>1</sup>	Max. mA <sup>1</sup>	μA <sup>2</sup>	μA <sup>2</sup>
14 mA	−0.3	VREF − 0.2	VREF + 0.2	3.6	0.7	VCCI − 1.1	14	14	54	51	10	10

**Notes:**

1. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
2. Currents are measured at 85°C junction temperature.



**Figure 2-20 • AC Loading**

**Table 2-73 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C <sub>LOAD</sub> (pF)
VREF − 0.2	VREF + 0.2	1.5	1.5	1.485	30

**Note:** \*Measuring point = Vtrip. See [Table 2-15 on page 2-18](#) for a complete table of trip points.

## Timing Characteristics

**Table 2-74 • SSTL3 Class I**

Commercial-Case Conditions: T<sub>J</sub> = 70°C, Worst-Case VCC = 1.425 V,  
Worst-Case VCCI = 3.0 V, VREF = 1.5 V

Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>ZH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	t <sub>ZLS</sub>	t <sub>ZHS</sub>	Units
Std.	0.66	2.31	0.04	1.25	0.43	2.35	1.84			4.59	4.07	ns
−1	0.56	1.96	0.04	1.06	0.36	2.00	1.56			3.90	3.46	ns
−2	0.49	1.72	0.03	0.93	0.32	1.75	1.37			3.42	3.04	ns

**Note:** For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

## SSTL3 Class II

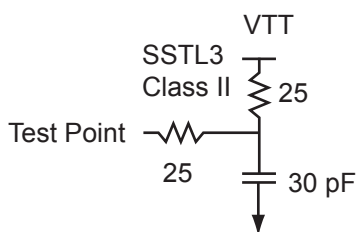
Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). ProASIC3E devices support Class II. This provides a differential amplifier input buffer and a push-pull output buffer.

**Table 2-75 • Minimum and Maximum DC Input and Output Levels**

SSTL3 Class II	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL	IIH
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>1</sup>	Max. mA <sup>1</sup>	μA <sup>2</sup>	μA <sup>2</sup>
21 mA	−0.3	VREF − 0.2	VREF + 0.2	3.6	0.5	VCCI − 0.9	21	21	109	103	10	10

**Notes:**

1. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
2. Currents are measured at 85°C junction temperature.



**Figure 2-21 • AC Loading**

**Table 2-76 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C <sub>LOAD</sub> (pF)
VREF − 0.2	VREF + 0.2	1.5	1.5	1.485	30

**Note:** \*Measuring point = V<sub>trip</sub>. See [Table 2-15 on page 2-18](#) for a complete table of trip points.

## Timing Characteristics

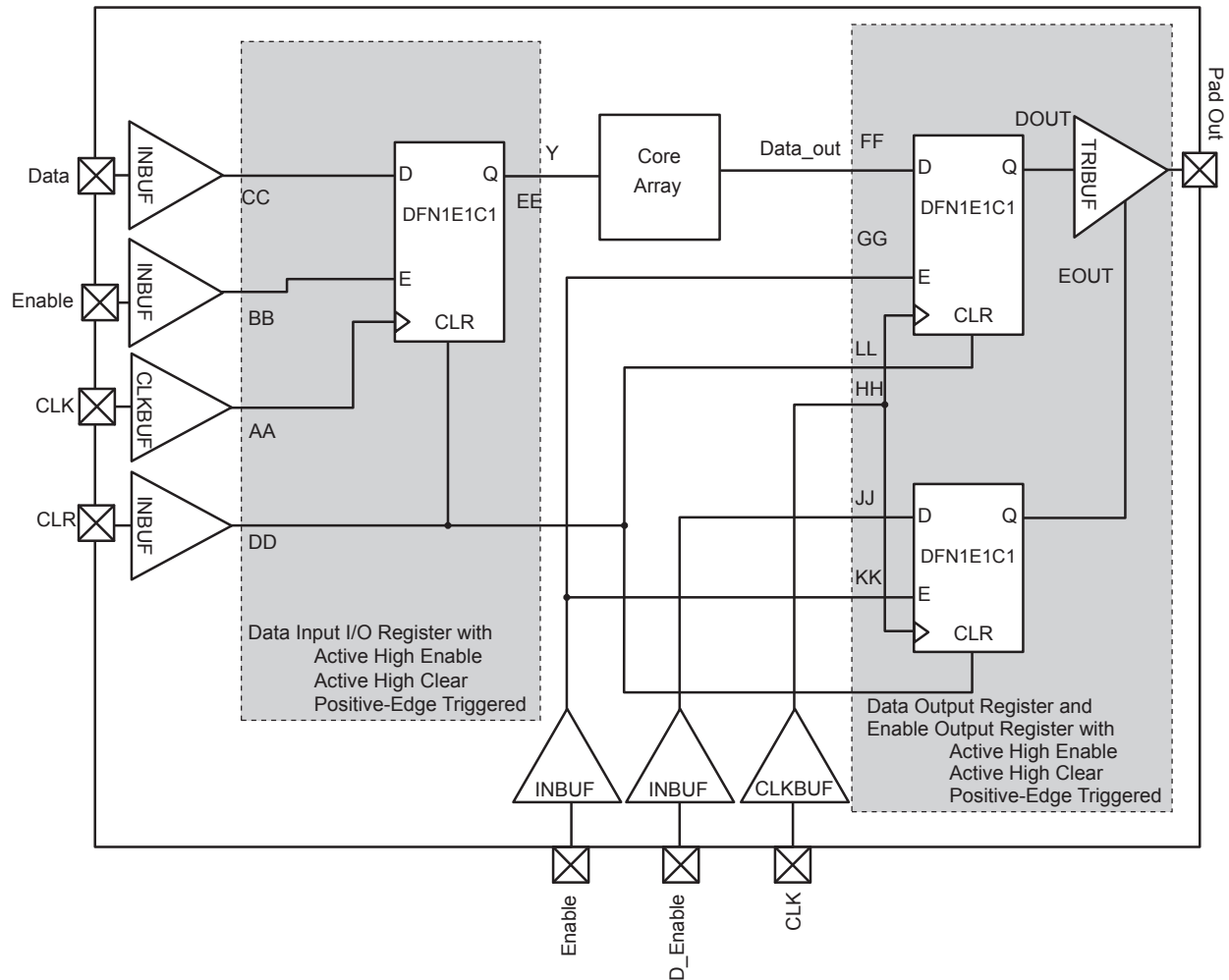
**Table 2-77 • SSTL3 Class II**

Commercial-Case Conditions: T<sub>J</sub> = 70°C, Worst-Case VCC = 1.425 V,  
Worst-Case VCCI = 3.0 V, VREF = 1.5 V

Speed Grade	t <sub>DOUT</sub>	t <sub>DP</sub>	t <sub>DIN</sub>	t <sub>PY</sub>	t <sub>EOUT</sub>	t <sub>ZL</sub>	t <sub>ZH</sub>	t <sub>LZ</sub>	t <sub>HZ</sub>	t <sub>ZLS</sub>	t <sub>ZHS</sub>	Units
Std.	0.66	2.07	0.04	1.25	0.43	2.10	1.67			4.34	3.91	ns
−1	0.56	1.76	0.04	1.06	0.36	1.79	1.42			3.69	3.32	ns
−2	0.49	1.54	0.03	0.93	0.32	1.57	1.25			3.24	2.92	ns

**Note:** For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.

## Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

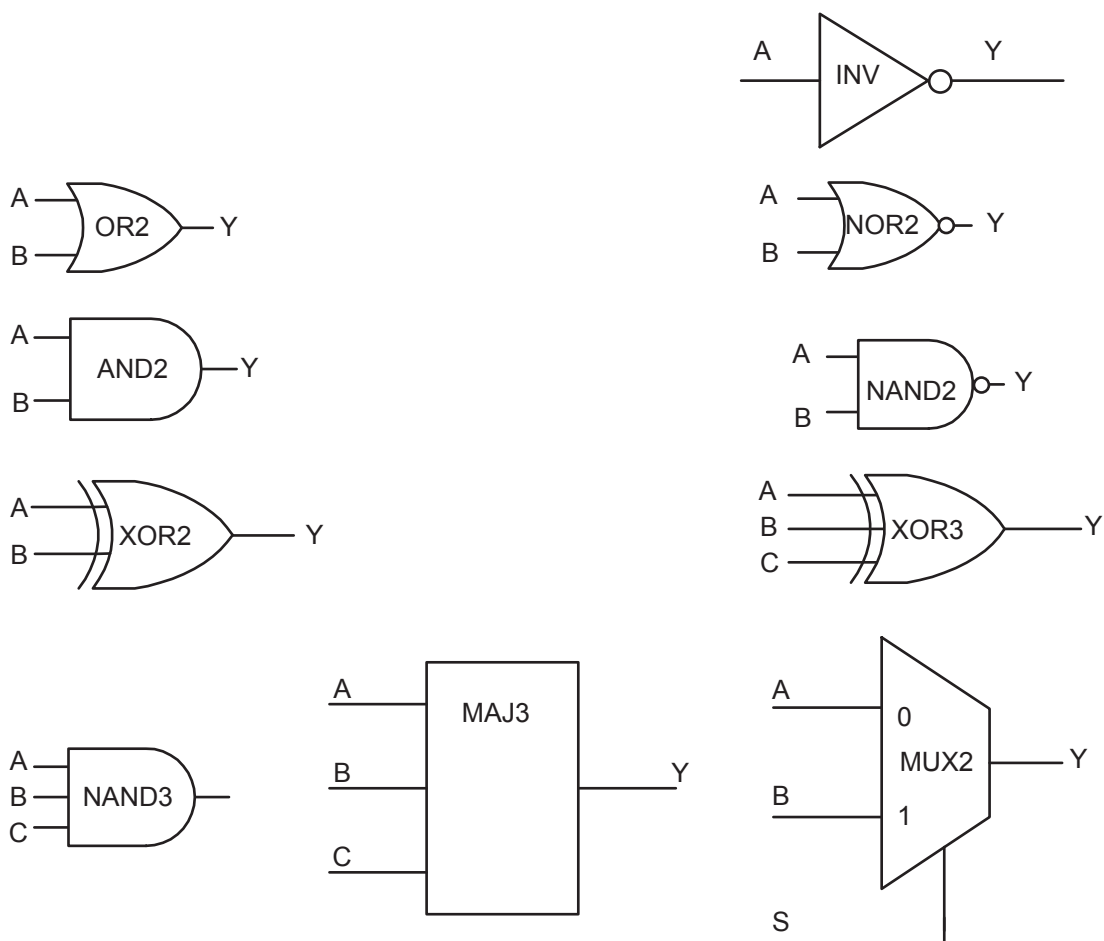


**Figure 2-26 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear**

## VersaTile Characteristics

### VersaTile Specifications as a Combinatorial Module

The ProASIC3E library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the [Fusion](#), [IGLOO®/e](#), and [ProASIC3/E Macro Library Guide](#).



**Figure 2-34 • Sample of Combinatorial Cells**

## Clock Conditioning Circuits

### CCC Electrical Specifications

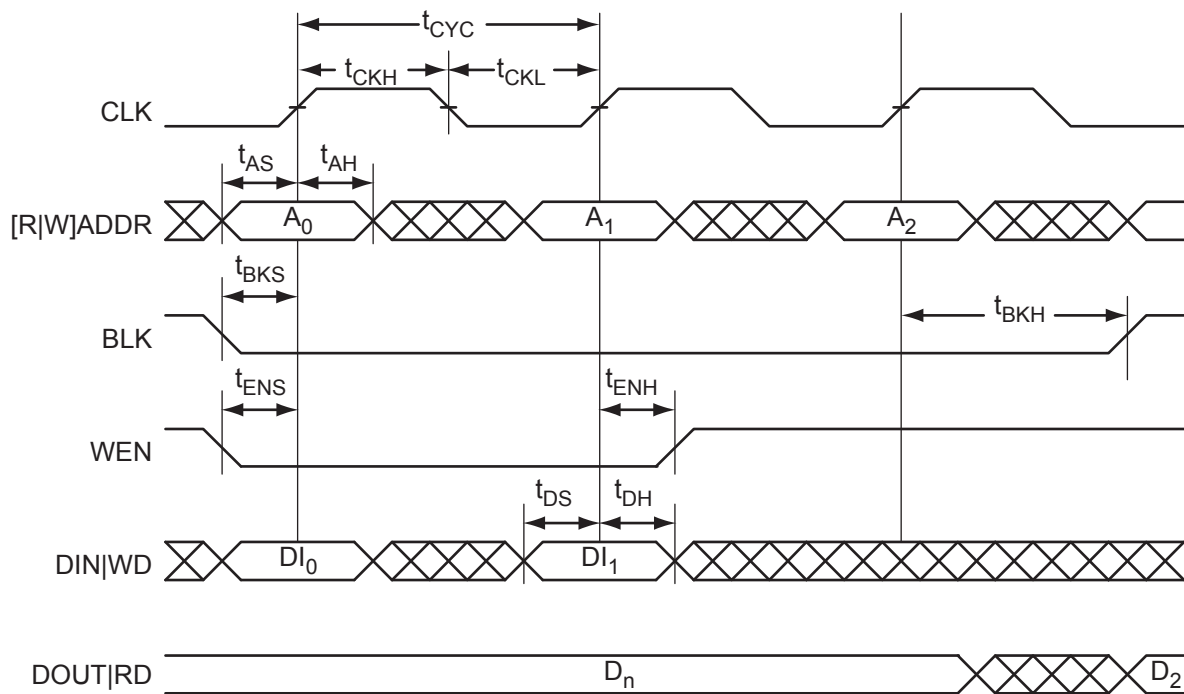
#### Timing Characteristics

**Table 2-98 • ProASIC3E CCC/PLL Specification**

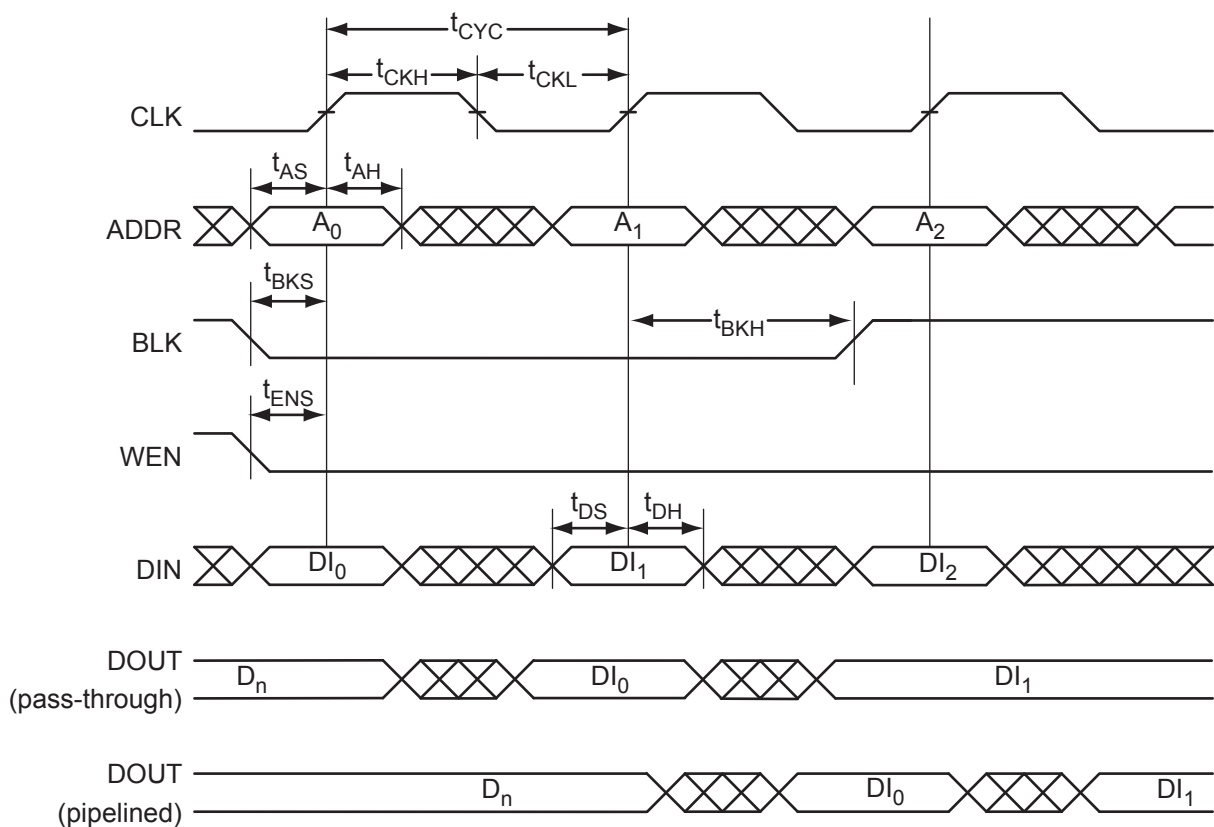
Parameter	Minimum	Typical	Maximum	Units
Clock Conditioning Circuitry Input Frequency $f_{IN\_CCC}$	1.5		350	MHz
Clock Conditioning Circuitry Output Frequency $f_{OUT\_CCC}$	0.75		350	MHz
Delay Increments in Programmable Delay Blocks <sup>1, 2</sup>		160 <sup>3</sup>		ps
Serial Clock (SCLK) for Dynamic PLL <sup>4</sup>			125	MHz
Number of Programmable Values in Each Programmable Delay Block			32	
Input Period Jitter			1.5	ns
CCC Output Peak-to-Peak Period Jitter $F_{CCC\_OUT}$	Max Peak-to-Peak Period Jitter			
	1 Global Network Used		3 Global Networks Used	
0.75 MHz to 24 MHz	0.50%		0.70%	
24 MHz to 100 MHz	1.00%		1.20%	
100 MHz to 250 MHz	1.75%		2.00%	
250 MHz to 350 MHz	2.50%		5.60%	
Acquisition Time	LockControl = 0		300	μs
	LockControl = 1		6.0	ms
Tracking Jitter <sup>5</sup>	LockControl = 0		1.6	ns
	LockControl = 1		0.8	ns
Output Duty Cycle	48.5		51.5	%
Delay Range in Block: Programmable Delay 1 <sup>1, 2</sup>	0.6		5.56	ns
Delay Range in Block: Programmable Delay 2 <sup>1, 2</sup>	0.025		5.56	ns
Delay Range in Block: Fixed Delay <sup>1, 4</sup>		2.2		ns

#### Notes:

1. This delay is a function of voltage and temperature. See [Table 2-6 on page 2-5](#) for deratings
2.  $T_J = 25^\circ\text{C}$ ,  $V_{CC} = 1.5\text{ V}$ .
3. When the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available. Refer to the Libero SoC Online Help for more information.
4. Maximum value obtained for a –2 speed-grade device in worst-case commercial conditions. For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-5](#) for derating values.
5. Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to the PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.



**Figure 2-43 • RAM Write, Output Retained. Applicable to Both RAM4K9 and RAM512x18.**



**Figure 2-44 • RAM Write, Output as Write Data. Applicable to RAM4K9 Only.**

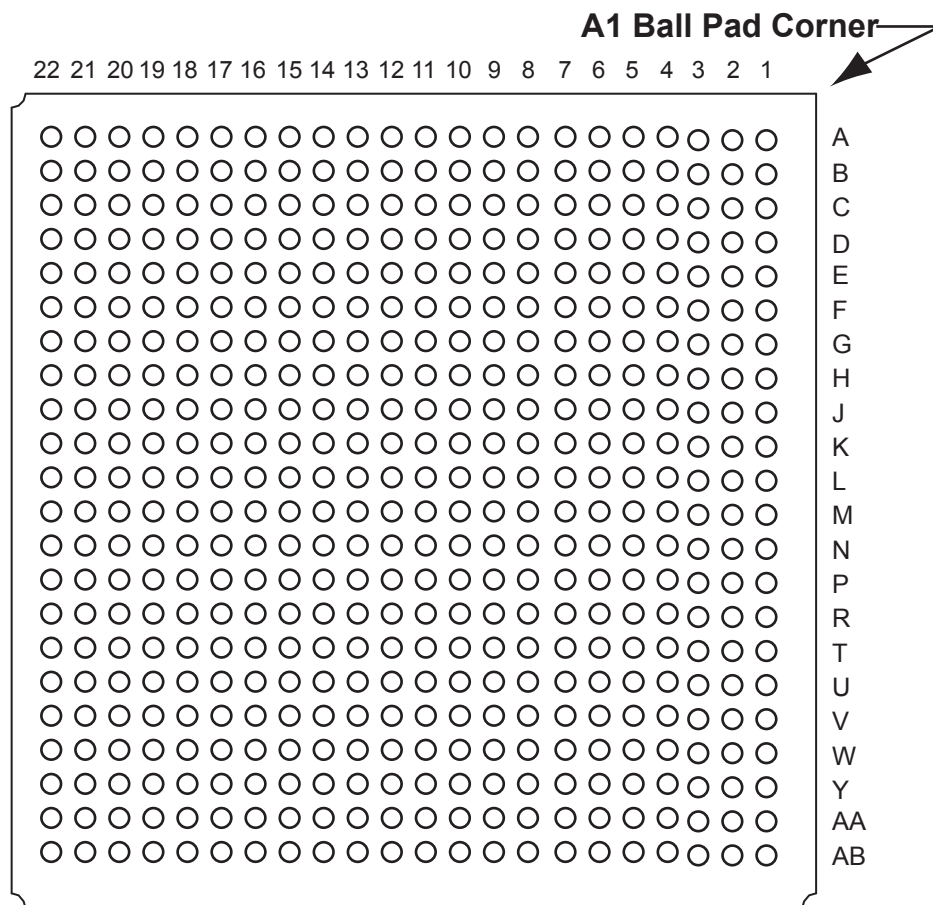


FG256	
Pin Number	A3PE600 Function
G13	GCC1/IO50PPB2V1
G14	IO44NDB2V1
G15	IO44PDB2V1
G16	IO49NSB2V1
H1	GFB0/IO119NPB7V0
H2	GFA0/IO118NDB6V1
H3	GFB1/IO119PPB7V0
H4	VCOMPLF
H5	GFC0/IO120NPB7V0
H6	VCC
H7	GND
H8	GND
H9	GND
H10	GND
H11	VCC
H12	GCC0/IO50NPB2V1
H13	GCB1/IO51PPB2V1
H14	GCA0/IO52NPB3V0
H15	VCOMPLC
H16	GCB0/IO51NPB2V1
J1	GFA2/IO117PSB6V1
J2	GFA1/IO118PDB6V1
J3	VCCPLF
J4	IO116NDB6V1
J5	GFB2/IO116PDB6V1
J6	VCC
J7	GND
J8	GND
J9	GND
J10	GND
J11	VCC
J12	GCB2/IO54PPB3V0
J13	GCA1/IO52PPB3V0
J14	GCC2/IO55PPB3V0
J15	VCCPLC
J16	GCA2/IO53PSB3V0

FG256	
Pin Number	A3PE600 Function
K1	GFC2/IO115PSB6V1
K2	IO113PPB6V1
K3	IO112PDB6V1
K4	IO112NDB6V1
K5	VCCIB6
K6	VCC
K7	GND
K8	GND
K9	GND
K10	GND
K11	VCC
K12	VCCIB3
K13	IO54NPB3V0
K14	IO57NPB3V0
K15	IO55NPB3V0
K16	IO57PPB3V0
L1	IO113NPB6V1
L2	IO109PPB6V0
L3	IO108PDB6V0
L4	IO108NDB6V0
L5	VCCIB6
L6	GND
L7	VCC
L8	VCC
L9	VCC
L10	VCC
L11	GND
L12	VCCIB3
L13	GDB0/IO66NPB3V1
L14	IO60NDB3V1
L15	IO60PDB3V1
L16	IO61PDB3V1
M1	IO109NPB6V0
M2	IO106NDB6V0
M3	IO106PDB6V0
M4	GEC0/IO104NPB6V0

FG256	
Pin Number	A3PE600 Function
M5	VMV5
M6	VCCIB5
M7	VCCIB5
M8	IO84NDB5V0
M9	IO84PDB5V0
M10	VCCIB4
M11	VCCIB4
M12	VMV3
M13	VCCPLD
M14	GDB1/IO66PPB3V1
M15	GDC1/IO65PDB3V1
M16	IO61NDB3V1
N1	IO105PDB6V0
N2	IO105NDB6V0
N3	GEC1/IO104PPB6V0
N4	VCOMPLE
N5	GNDQ
N6	GEA2/IO101PPB5V2
N7	IO92NDB5V1
N8	IO90NDB5V1
N9	IO82NDB5V0
N10	IO74NDB4V1
N11	IO74PDB4V1
N12	GNDQ
N13	VCOMPLD
N14	VJTAG
N15	GDC0/IO65NDB3V1
N16	GDA1/IO67PDB3V1
P1	GEB1/IO103PDB6V0
P2	GEB0/IO103NDB6V0
P3	VMV6
P4	VCCPLE
P5	IO101NPB5V2
P6	IO95PPB5V1
P7	IO92PDB5V1
P8	IO90PDB5V1

## FG484



*Note:* This is the bottom view of the package.

### Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.microsemi.com/products/fpga-soc/solutions>.

FG484	
Pin Number	A3PE600 Function
C21	NC
C22	VCCIB2
D1	NC
D2	NC
D3	NC
D4	GND
D5	GAA0/IO00NDB0V0
D6	GAA1/IO00PDB0V0
D7	GAB0/IO01NDB0V0
D8	IO05PDB0V0
D9	IO10PDB0V1
D10	IO12PDB0V2
D11	IO16NDB0V2
D12	IO23NDB1V0
D13	IO23PDB1V0
D14	IO28NDB1V1
D15	IO28PDB1V1
D16	GBB1/IO34PDB1V1
D17	GBA0/IO35NDB1V1
D18	GBA1/IO35PDB1V1
D19	GND
D20	NC
D21	NC
D22	NC
E1	NC
E2	NC
E3	GND
E4	GAB2/IO133PDB7V1
E5	GAA2/IO134PDB7V1
E6	GNDQ
E7	GAB1/IO01PDB0V0
E8	IO05NDB0V0
E9	IO10NDB0V1
E10	IO12NDB0V2
E11	IO16PDB0V2
E12	IO20NDB1V0

FG484	
Pin Number	A3PE600 Function
E13	IO24NDB1V0
E14	IO24PDB1V0
E15	GBC1/IO33PDB1V1
E16	GBB0/IO34NDB1V1
E17	GNDQ
E18	GBA2/IO36PDB2V0
E19	IO42NDB2V0
E20	GND
E21	NC
E22	NC
F1	NC
F2	IO131NDB7V1
F3	IO131PDB7V1
F4	IO133NDB7V1
F5	IO134NDB7V1
F6	VMV7
F7	VCCPLA
F8	GAC0/IO02NDB0V0
F9	GAC1/IO02PDB0V0
F10	IO15NDB0V2
F11	IO15PDB0V2
F12	IO20PDB1V0
F13	IO25NDB1V0
F14	IO27PDB1V0
F15	GBC0/IO33NDB1V1
F16	VCCPLB
F17	VMV2
F18	IO36NDB2V0
F19	IO42PDB2V0
F20	NC
F21	NC
F22	NC
G1	IO127NDB7V1
G2	IO127PDB7V1
G3	NC
G4	IO128PDB7V1

FG484	
Pin Number	A3PE600 Function
G5	IO129PDB7V1
G6	GAC2/IO132PDB7V1
G7	VCOMPLA
G8	GNDQ
G9	IO09NDB0V1
G10	IO09PDB0V1
G11	IO13PDB0V2
G12	IO21PDB1V0
G13	IO25PDB1V0
G14	IO27NDB1V0
G15	GNDQ
G16	VCOMPLB
G17	GBB2/IO37PDB2V0
G18	IO39PDB2V0
G19	IO39NDB2V0
G20	IO43PDB2V0
G21	IO43NDB2V0
G22	NC
H1	NC
H2	NC
H3	VCC
H4	IO128NDB7V1
H5	IO129NDB7V1
H6	IO132NDB7V1
H7	IO130PDB7V1
H8	VMV0
H9	VCCIB0
H10	VCCIB0
H11	IO13NDB0V2
H12	IO21NDB1V0
H13	VCCIB1
H14	VCCIB1
H15	VMV1
H16	GBC2/IO38PDB2V0
H17	IO37NDB2V0
H18	IO41NDB2V0

FG484		FG484		FG484	
Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function
C21	IO94PPB2V1	E13	IO58NDB1V2	G5	IO297PDB7V2
C22	VCCIB2	E14	IO58PDB1V2	G6	GAC2/IO307PDB7V4
D1	IO293PDB7V2	E15	GBC1/IO79PDB1V4	G7	VCOMPLA
D2	IO303NDB7V3	E16	GBB0/IO80NDB1V4	G8	GNDQ
D3	IO305NDB7V3	E17	GNDQ	G9	IO26NDB0V3
D4	GND	E18	GBA2/IO82PDB2V0	G10	IO26PDB0V3
D5	GAA0/IO00NDB0V0	E19	IO86NDB2V0	G11	IO36PDB0V4
D6	GAA1/IO00PDB0V0	E20	GND	G12	IO42PDB1V0
D7	GAB0/IO01NDB0V0	E21	IO90NDB2V1	G13	IO50PDB1V1
D8	IO20PDB0V2	E22	IO98PDB2V2	G14	IO60NDB1V2
D9	IO22PDB0V2	F1	IO299NPB7V3	G15	GNDQ
D10	IO30PDB0V3	F2	IO301NDB7V3	G16	VCOMPLB
D11	IO38NDB0V4	F3	IO301PDB7V3	G17	GBB2/IO83PDB2V0
D12	IO52NDB1V1	F4	IO308NDB7V4	G18	IO92PDB2V1
D13	IO52PDB1V1	F5	IO309NDB7V4	G19	IO92NDB2V1
D14	IO66NDB1V3	F6	VMV7	G20	IO102PDB2V2
D15	IO66PDB1V3	F7	VCCPLA	G21	IO102NDB2V2
D16	GBB1/IO80PDB1V4	F8	GAC0/IO02NDB0V0	G22	IO105NDB2V2
D17	GBA0/IO81NDB1V4	F9	GAC1/IO02PDB0V0	H1	IO286PSB7V1
D18	GBA1/IO81PDB1V4	F10	IO32NDB0V3	H2	IO291NPB7V2
D19	GND	F11	IO32PDB0V3	H3	VCC
D20	IO88PDB2V0	F12	IO44PDB1V0	H4	IO295NDB7V2
D21	IO90PDB2V1	F13	IO50NDB1V1	H5	IO297NDB7V2
D22	IO94NPB2V1	F14	IO60PDB1V2	H6	IO307NDB7V4
E1	IO293NDB7V2	F15	GBC0/IO79NDB1V4	H7	IO287PDB7V1
E2	IO299PPB7V3	F16	VCCPLB	H8	VMV0
E3	GND	F17	VMV2	H9	VCCIB0
E4	GAB2/IO308PDB7V4	F18	IO82NDB2V0	H10	VCCIB0
E5	GAA2/IO309PDB7V4	F19	IO86PDB2V0	H11	IO36NDB0V4
E6	GNDQ	F20	IO96PDB2V1	H12	IO42NDB1V0
E7	GAB1/IO01PDB0V0	F21	IO96NDB2V1	H13	VCCIB1
E8	IO20NDB0V2	F22	IO98NDB2V2	H14	VCCIB1
E9	IO22NDB0V2	G1	IO289NDB7V1	H15	VMV1
E10	IO30NDB0V3	G2	IO289PDB7V1	H16	GBC2/IO84PDB2V0
E11	IO38PDB0V4	G3	IO291PPB7V2	H17	IO83NDB2V0
E12	IO44NDB1V0	G4	IO295PDB7V2	H18	IO100NDB2V2

FG676	
Pin Number	A3PE1500 Function
A1	GND
A2	GND
A3	GAA0/IO00NDB0V0
A4	GAA1/IO00PDB0V0
A5	IO06NDB0V0
A6	IO09NDB0V1
A7	IO09PDB0V1
A8	IO14NDB0V1
A9	IO14PDB0V1
A10	IO22NDB0V2
A11	IO22PDB0V2
A12	IO26NDB0V3
A13	IO26PDB0V3
A14	IO30NDB0V3
A15	IO30PDB0V3
A16	IO34NDB1V0
A17	IO34PDB1V0
A18	IO38NDB1V0
A19	IO38PDB1V0
A20	IO41PDB1V1
A21	IO44PDB1V1
A22	IO49PDB1V2
A23	IO50PDB1V2
A24	GBC1/IO55PDB1V3
A25	GND
A26	GND
AA1	IO174PDB6V0
AA2	IO171PDB6V0
AA3	GEA1/IO167PPB6V0
AA4	GEC0/IO169NPB6V0
AA5	VCOMPLE
AA6	GND
AA7	IO165NDB5V3
AA8	GEB2/IO165PDB5V3
AA9	IO163PDB5V3
AA10	IO159NDB5V3

FG676	
Pin Number	A3PE1500 Function
AA11	IO153NDB5V2
AA12	IO147NDB5V1
AA13	IO139NDB5V0
AA14	IO137NDB5V0
AA15	IO123NDB4V1
AA16	IO123PDB4V1
AA17	IO117NDB4V0
AA18	IO117PDB4V0
AA19	GDB2/IO112PDB4V0
AA20	GNDQ
AA21	TDO
AA22	GND
AA23	GND
AA24	IO102NDB3V1
AA25	IO102PDB3V1
AA26	IO98NDB3V1
AB1	IO174NDB6V0
AB2	IO171NDB6V0
AB3	GEB1/IO168PPB6V0
AB4	GEA0/IO167NPB6V0
AB5	VCCPLE
AB6	GND
AB7	GND
AB8	IO156NDB5V2
AB9	IO156PDB5V2
AB10	IO150PDB5V1
AB11	IO155PDB5V2
AB12	IO142PDB5V0
AB13	IO135NDB5V0
AB14	IO135PDB5V0
AB15	IO132PDB4V2
AB16	IO129PDB4V2
AB17	IO121PDB4V1
AB18	IO119NDB4V1
AB19	IO112NDB4V0
AB20	VMV4

FG676	
Pin Number	A3PE1500 Function
AB21	TCK
AB22	TRST
AB23	GDC0/IO108NDB3V2
AB24	GDC1/IO108PDB3V2
AB25	IO104NDB3V2
AB26	IO104PDB3V2
AC1	IO170PDB6V0
AC2	GEB0/IO168NPB6V0
AC3	IO166NPB5V3
AC4	GNDQ
AC5	GND
AC6	IO160PDB5V3
AC7	IO161PDB5V3
AC8	IO154PDB5V2
AC9	GND
AC10	IO150NDB5V1
AC11	IO155NDB5V2
AC12	IO142NDB5V0
AC13	IO138NDB5V0
AC14	IO138PDB5V0
AC15	IO132NDB4V2
AC16	IO129NDB4V2
AC17	IO121NDB4V1
AC18	IO119PDB4V1
AC19	IO118NDB4V0
AC20	IO118PDB4V0
AC21	IO114PPB4V0
AC22	TMS
AC23	VJTAG
AC24	VMV3
AC25	IO106NDB3V2
AC26	IO106PDB3V2
AD1	IO170NDB6V0
AD2	GEA2/IO166PPB5V3
AD3	VMV5
AD4	GEC2/IO164PDB5V3

FG896		FG896		FG896	
Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function	Pin Number	A3PE3000 Function
A2	GND	AA9	GEB1/IO235PPB6V0	AB15	IO198PDB5V0
A3	GND	AA10	VCC	AB16	IO192NDB4V4
A4	IO14NPB0V1	AA11	IO226PPB5V4	AB17	IO192PDB4V4
A5	GND	AA12	VCCIB5	AB18	IO178NDB4V3
A6	IO07NPB0V0	AA13	VCCIB5	AB19	IO178PDB4V3
A7	GND	AA14	VCCIB5	AB20	IO174NDB4V2
A8	IO09NDB0V1	AA15	VCCIB5	AB21	IO162NPB4V1
A9	IO17NDB0V2	AA16	VCCIB4	AB22	VCC
A10	IO17PDB0V2	AA17	VCCIB4	AB23	VCCPLD
A11	IO21NDB0V2	AA18	VCCIB4	AB24	VCCIB3
A12	IO21PDB0V2	AA19	VCCIB4	AB25	IO150PDB3V4
A13	IO33NDB0V4	AA20	IO174PDB4V2	AB26	IO148PDB3V4
A14	IO33PDB0V4	AA21	VCC	AB27	IO147NDB3V4
A15	IO35NDB0V4	AA22	IO142NPB3V3	AB28	IO145PDB3V3
A16	IO35PDB0V4	AA23	IO144NDB3V3	AB29	IO143PDB3V3
A17	IO41NDB1V0	AA24	IO144PDB3V3	AB30	IO137PDB3V2
A18	IO43NDB1V0	AA25	IO146NDB3V4	AC1	IO254PDB6V2
A19	IO43PDB1V0	AA26	IO146PDB3V4	AC2	IO254NDB6V2
A20	IO45NDB1V0	AA27	IO147PDB3V4	AC3	IO240PDB6V0
A21	IO45PDB1V0	AA28	IO139NDB3V3	AC4	GEC1/IO236PDB6V0
A22	IO57NDB1V2	AA29	IO139PDB3V3	AC5	IO237PDB6V0
A23	IO57PDB1V2	AA30	IO133NDB3V2	AC6	IO237NDB6V0
A24	GND	AB1	IO256NDB6V2	AC7	VCOMPLE
A25	IO69PPB1V3	AB2	IO244PDB6V1	AC8	GND
A26	GND	AB3	IO244NDB6V1	AC9	IO226NPB5V4
A27	GBC1/IO79PPB1V4	AB4	IO241PDB6V0	AC10	IO222NDB5V3
A28	GND	AB5	IO241NDB6V0	AC11	IO216NPB5V2
A29	GND	AB6	IO243NPB6V1	AC12	IO210NPB5V2
AA1	IO256PDB6V2	AB7	VCCIB6	AC13	IO204NDB5V1
AA2	IO248PDB6V1	AB8	VCCPLE	AC14	IO204PDB5V1
AA3	IO248NDB6V1	AB9	VCC	AC15	IO194NDB5V0
AA4	IO246NDB6V1	AB10	IO222PDB5V3	AC16	IO188NDB4V4
AA5	GEA1/IO234PDB6V0	AB11	IO218PPB5V3	AC17	IO188PDB4V4
AA6	GEA0/IO234NDB6V0	AB12	IO206NDB5V1	AC18	IO182PPB4V3
AA7	IO243PPB6V1	AB13	IO206PDB5V1	AC19	IO170NPB4V2
AA8	IO245NDB6V1	AB14	IO198NDB5V0	AC20	IO164NDB4V1

FG896	
Pin Number	A3PE3000 Function
W29	IO131PDB3V2
W30	IO123NDB3V1
Y1	IO266PDB6V4
Y2	IO250PDB6V2
Y3	IO250NDB6V2
Y4	IO246PDB6V1
Y5	IO247NDB6V1
Y6	IO247PDB6V1
Y7	IO249NPB6V1
Y8	IO245PDB6V1
Y9	IO253NDB6V2
Y10	GEB0/IO235NPB6V0
Y11	VCC
Y12	VCC
Y13	VCC
Y14	VCC
Y15	VCC
Y16	VCC
Y17	VCC
Y18	VCC
Y19	VCC
Y20	VCC
Y21	IO142PPB3V3
Y22	IO134NDB3V2
Y23	IO138NDB3V3
Y24	IO140NDB3V3
Y25	IO140PDB3V3
Y26	IO136PPB3V2
Y27	IO141NDB3V3
Y28	IO135NDB3V2
Y29	IO131NDB3V2
Y30	IO133PDB3V2

Revision	Changes	Page
<b>Revision 3 (Apr 2008)</b> Packaging v1.2	The following pins had duplicates and the extra pins were deleted from the "PQ208" A3PE3000 table: 36, 62, 171 Note: There were no pin function changes in this update.	4-2
	The following pins had duplicates and the extra pins were deleted from the "FG324" table: E2, E3, E16, E17, P2, P3, T16, U17 Note: There were no pin function changes in this update.	4-12
	The "FG256" pin table was updated for the A3PE600 device because the old PAT were based on the IFX die, and this is the final UMC die version.	4-9
	The "FG484" was updated for the A3PE600 device because the old PAT were based on the IFX die, and this is the final UMC die version.	4-22
	The following pins had duplicates and the extra pins were deleted from the "FG896" table: AD6, AE5, AE28, AF29, F5, F26, G6, G25 Note: There were no pin function changes in this update.	4-41
<b>Revision 2 (Mar 2008)</b> Product Brief rev. 1	The FG324 package was added to the "ProASIC3E Product Family" table, the "I/Os Per Package1" table, and the "Temperature Grade Offerings" table for A3PE3000.	I, II, IV
<b>Revision 1 (Feb 2008)</b> DC and Switching Characteristics v1.1	In Table 2-3 • Flash Programming Limits – Retention, Storage and Operating Temperature 1, Maximum Operating Junction Temperature was changed from 110°C to 100°C for both commercial and industrial grades.	2
	The "PLL Behavior at Brownout Condition" section is new.	2-4
	In the "PLL Contribution—PPLL" section, the following was deleted: FCLKIN is the input clock frequency.	2-10
	In Table 2-14 • Summary of Maximum and Minimum DC Input Levels, the note was incorrect. It previously said T <sub>J</sub> and it was corrected and changed to T <sub>A</sub> .	2-17
	In Table 2-98 • ProASIC3E CCC/PLL Specification, the SCLK parameter and note 1 are new.	2-70
	Table 2-103 • JTAG 1532 was populated with the parameter data, which was not in the previous version of the document.	2-83
<b>Revision 1 (cont'd)</b> Packaging v1.1	The "PQ208" pin table for A3PE3000 was updated.	4-2
	The "FG324" pin table for A3PE3000 is new.	4-13
	The "FG484" pin table for A3PE3000 is new.	4-17
	The "FG896" pin table for A3PE3000 is new.	4-41
<b>Revision 0 (Jan 2008)</b>	This document was previously in datasheet v2.1. As a result of moving to the handbook format, Actel has restarted the version numbers. The new version number is 51700098-001-0.	N/A
v2.1 (July 2007)	CoreMP7 information was removed from the "Features and Benefits" section.	1-I
	The M1 device part numbers have been updated in ProASIC3E Product Family, "Packaging Tables", "Temperature Grade Offerings", "Speed Grade and Temperature Grade Matrix", and "Speed Grade and Temperature Grade Matrix".	1-I





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